

4-PIN SOP, 3.0 pF LOW OUTPUT CAPACITANCE  
1-ch Optical Coupled MOS FET

-NEPOC Series-

**DESCRIPTION**

The PS7200A-1A is a low output capacitance solid state relay containing GaAs LEDs on the light emitting side (input side) and MOS FETs on the output side.

It is suitable for high-frequency signal control, due to its low  $C \times R$ , low output capacitance, and low off-state leakage current.

**FEATURES**

- Low  $C \times R$  ( $C \times R = 30 \text{ pF} \cdot \Omega$ )
- Low output capacitance ( $C_{\text{out}} = 3.0 \text{ pF TYP.}$ )
- Low off-state leakage current ( $I_{\text{loff}} = 0.1 \text{ nA TYP.}$ )
- High-speed turn-on time ( $t_{\text{on}} = 0.01 \text{ ms TYP.}$ )
- 1 channel type (1 a output)
- Low LED operating current ( $I_F = 2 \text{ mA}$ )
- Designed for AC/DC switching line changer
- Small and thin package (4-pin SOP, Height = 2.1 mm)
- Low offset voltage
- Ordering number of taping product : PS7200A-1A-E3, E4: 900 pcs/reel  
: PS7200A-1A-F3, F4: 3 500 pcs/reel

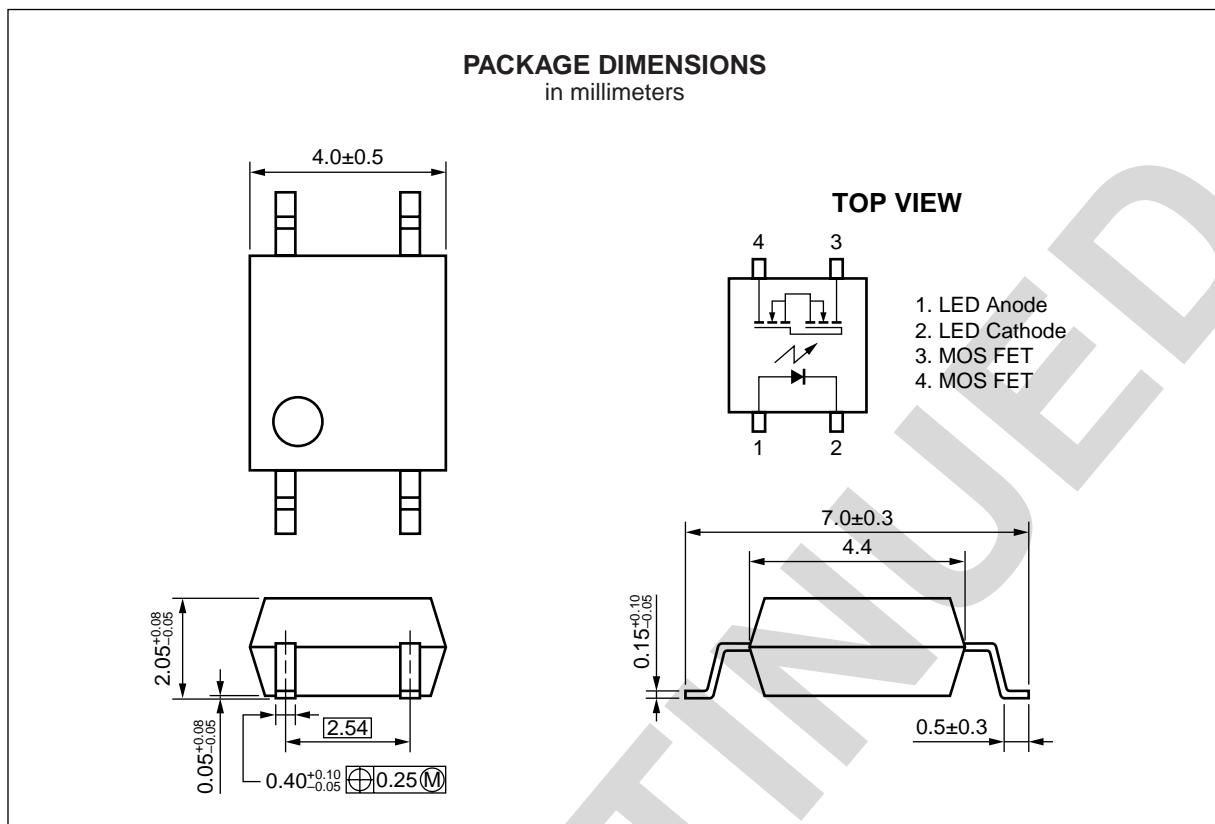
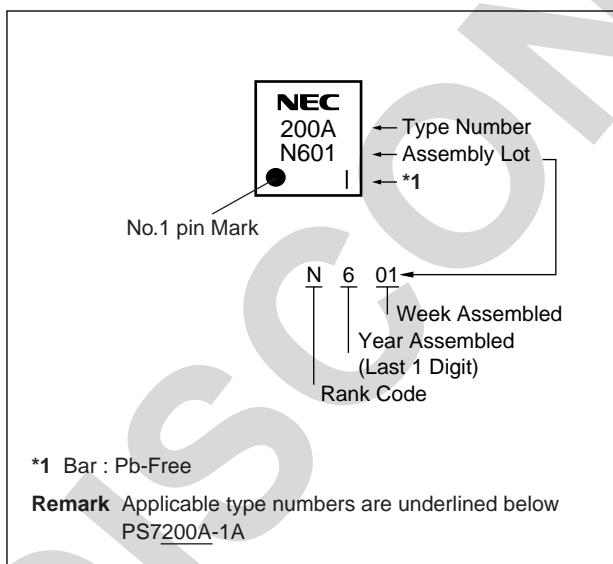
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- Pb-Free product
- Safety standards
  - UL approved: File No. E72422
  - BSI approved: No. 8241/8242
  - CSA approved: No. CA 101391

**APPLICATIONS**

- Measurement equipment

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<R> **MARKING EXAMPLE (LASER MARKING)**

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**ORDERING INFORMATION**

Part Number	Order Number	Solder Plating Specification	Packing Style	Safety Standard Approval	Application Part Number <sup>*1</sup>
PS7200A-1A	PS7200A-1A-A	Pb-Free	Magazine case 100 pcs	(UL, BSI, CSA approved)	PS7200A-1A
PS7200A-1A-E3	PS7200A-1A-E3-A		Embossed Tape 900 pcs/reel		
PS7200A-1A-E4	PS7200A-1A-E4-A				
PS7200A-1A-F3	PS7200A-1A-F3-A		Embossed Tape 3 500 pcs/reel		
PS7200A-1A-F4	PS7200A-1A-F4-A				

\*1 For the application of the Safety Standard, following part number should be used.

**ABSOLUTE MAXIMUM RATINGS (T<sub>A</sub> = 25°C, unless otherwise specified)**

Parameter		Symbol	Ratings	Unit
Diode	Forward Current (DC)	I <sub>F</sub>	50	mA
	Reverse Voltage	V <sub>R</sub>	5.0	V
	Power Dissipation	P <sub>D</sub>	50	mW
	Peak Forward Current <sup>*1</sup>	I <sub>FP</sub>	1	A
MOS FET	Break Down Voltage	V <sub>L</sub>	40	V
	Continuous Load Current	I <sub>L</sub>	100	mA
	Pulse Load Current <sup>*2</sup> (AC/DC Connection)	I <sub>LP</sub>	200	mA
	Power Dissipation	P <sub>D</sub>	100	mW
Isolation Voltage <sup>*3</sup>		BV	1 500	Vr.m.s.
Total Power Dissipation		P <sub>T</sub>	150	mW
Operating Ambient Temperature		T <sub>A</sub>	-40 to +85	°C
Storage Temperature		T <sub>stg</sub>	-40 to +100	°C

\*1 PW = 100  $\mu$ s, Duty Cycle = 1%

\*2 PW = 100 ms, 1 shot

\*3 AC voltage for 1 minute at T<sub>A</sub> = 25°C, RH = 60% between input and output

Pins 1-2 shorted together, 3-4 shorted together.

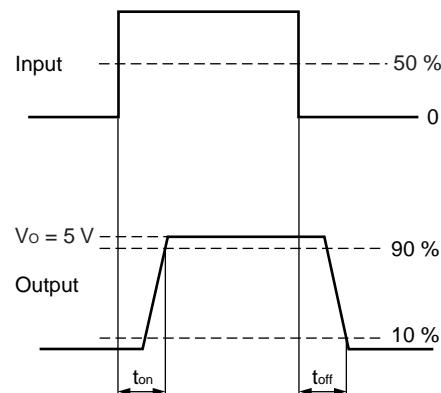
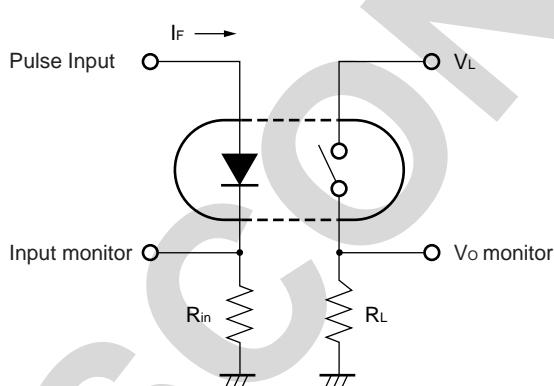
RECOMMENDED OPERATING CONDITIONS ( $T_A = 25^\circ\text{C}$ )

Parameter	Symbol	MIN.	TYP.	MAX.	Unit
LED Operating Current	$I_F$	2	10	20	mA
LED Off Voltage	$V_F$	0		0.5	V

ELECTRICAL CHARACTERISTICS ( $T_A = 25^\circ\text{C}$ )

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Diode	Forward Voltage	$V_F$ $I_F = 10 \text{ mA}$		1.2	1.4	V
	Reverse Current	$I_R$ $V_R = 5 \text{ V}$			5.0	$\mu\text{A}$
MOS FET	Off-state Leakage Current	$I_{Loff}$ $V_D = 40 \text{ V}$		0.1	100	nA
	Output Capacitance	$C_{out}$ $V_D = 0 \text{ V}, f = 1 \text{ MHz}$		3.0		pF
Coupled	LED On-state Current	$I_{Fon}$ $I_L = 100 \text{ mA}$			2.0	mA
	On-state Resistance	$R_{on1}$ $I_F = 10 \text{ mA}, I_L = 10 \text{ mA}$		9.3	12	$\Omega$
		$R_{on2}$ $I_F = 10 \text{ mA}, I_L = 100 \text{ mA}, t \leq 10 \text{ ms}$				
	Turn-on Time <sup>1,2</sup>	$t_{on}$ $I_F = 10 \text{ mA}, V_o = 5 \text{ V}, R_L = 500 \Omega$		0.01	0.5	ms
	Turn-off Time <sup>1,2</sup>	$t_{off}$ $PW \geq 10 \text{ ms}$		0.07	0.2	
	Isolation Resistance	$R_{i-o}$ $V_{i-o} = 1.0 \text{ kVdc}$	$10^9$			$\Omega$
	Isolation Capacitance	$C_{i-o}$ $V = 0 \text{ V}, f = 1 \text{ MHz}$		0.5		pF

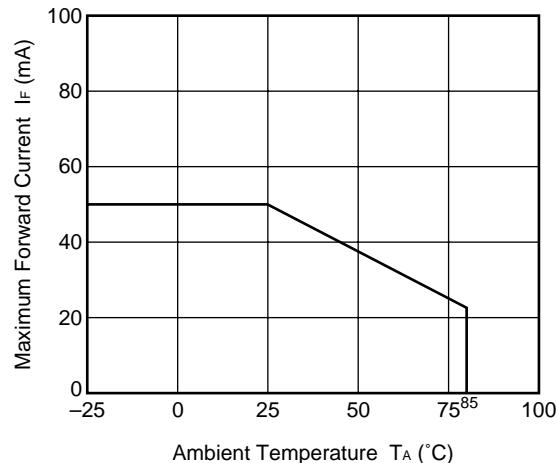
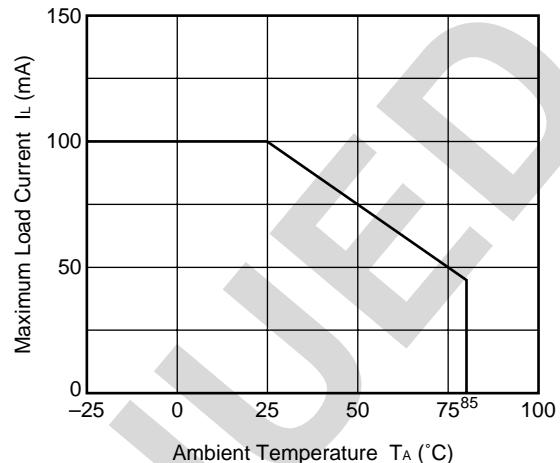
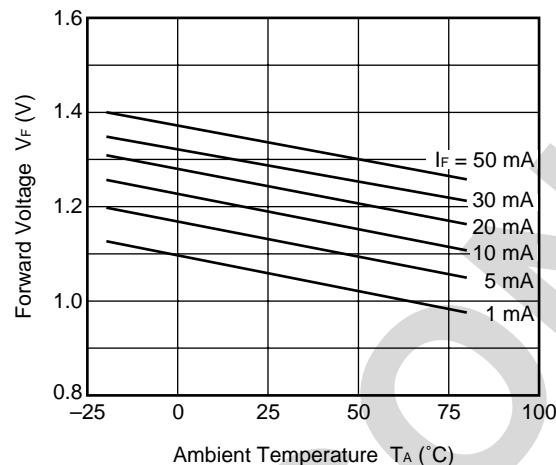
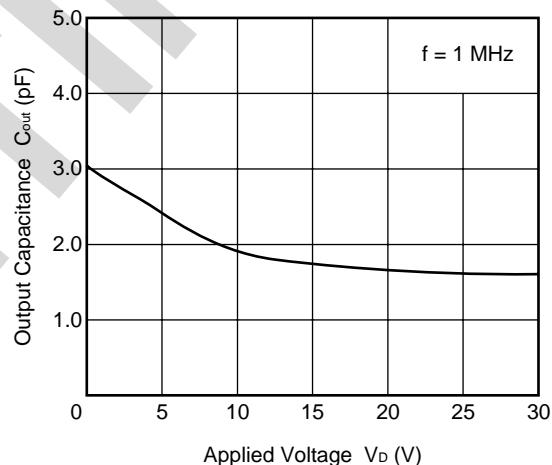
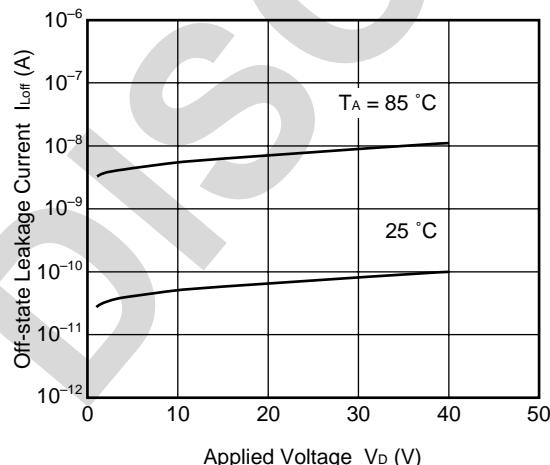
\*1 Test Circuit for Switching Time



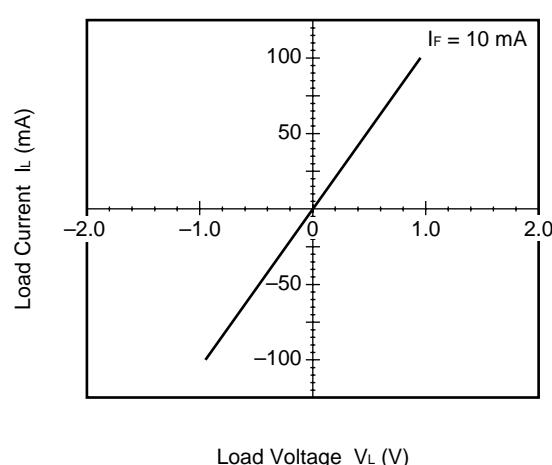
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\*2 The turn-on time and turn-off time are specified as input-pulse width  $\geq 10 \text{ ms}$ .

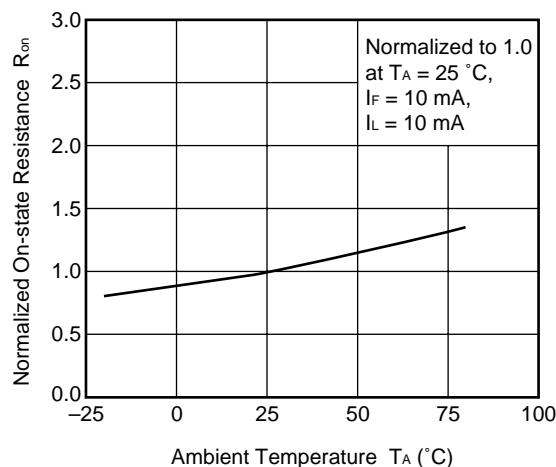
Be aware that when the device operates with an input-pulse width less than 10 ms, the turn-on time and turn-off time will increase.

TYPICAL CHARACTERISTICS ( $T_A = 25^\circ\text{C}$ , unless otherwise specified)MAXIMUM FORWARD CURRENT vs.  
AMBIENT TEMPERATUREMAXIMUM LOAD CURRENT vs.  
AMBIENT TEMPERATUREFORWARD VOLTAGE vs.  
AMBIENT TEMPERATUREOUTPUT CAPACITANCE vs.  
APPLIED VOLTAGEOFF-STATE LEAKAGE CURRENT vs.  
APPLIED VOLTAGE

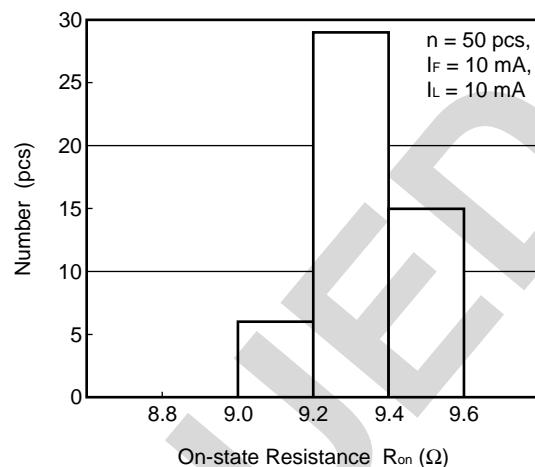
LOAD CURRENT vs. LOAD VOLTAGE



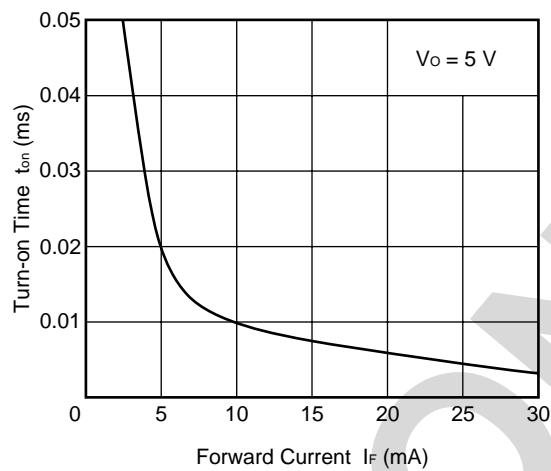
**Remark** The graphs indicate nominal characteristics.

NORMALIZED ON-STATE RESISTANCE vs.  
AMBIENT TEMPERATURE

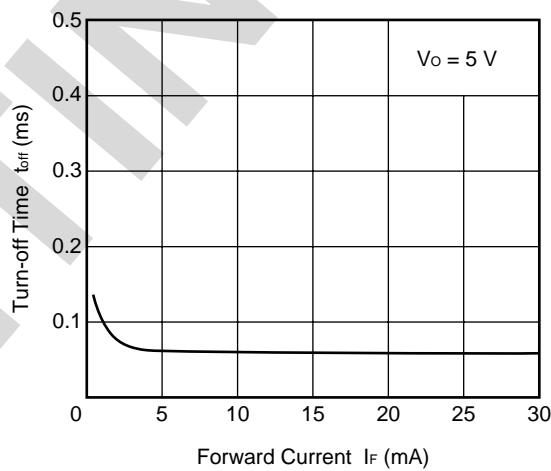
ON-STATE RESISTANCE DISTRIBUTION



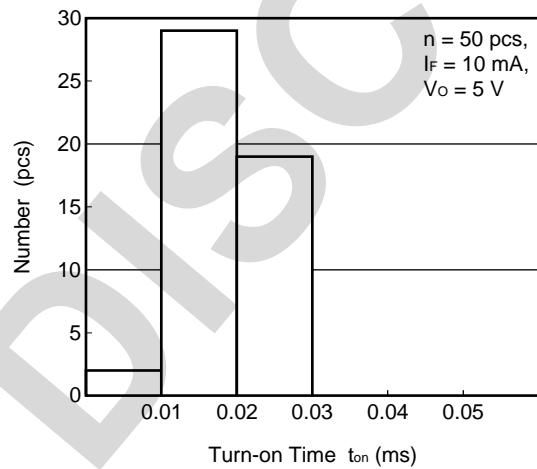
TURN-ON TIME vs. FORWARD CURRENT



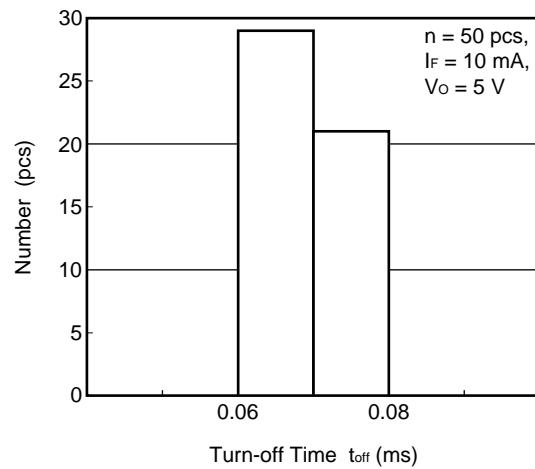
TURN-OFF TIME vs. FORWARD CURRENT



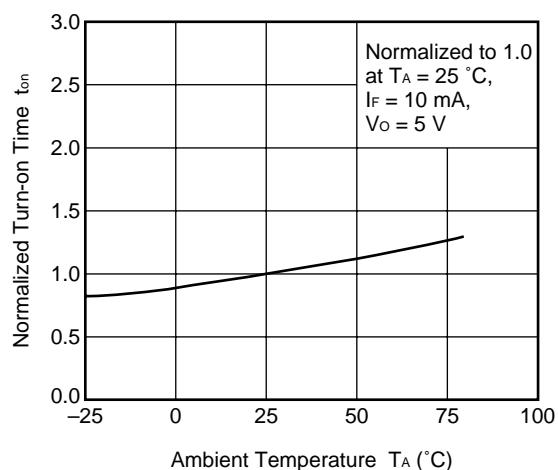
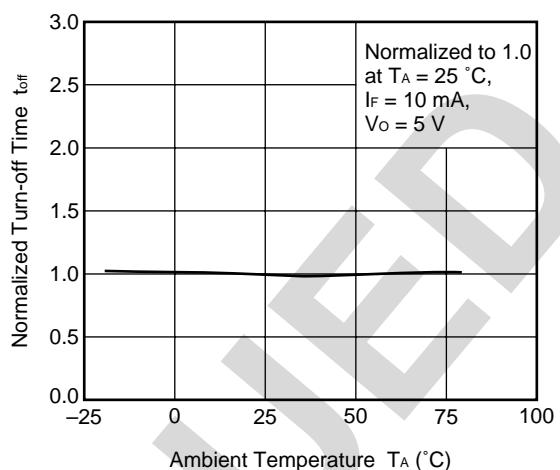
TURN-ON TIME DISTRIBUTION



TURN-OFF TIME DISTRIBUTION



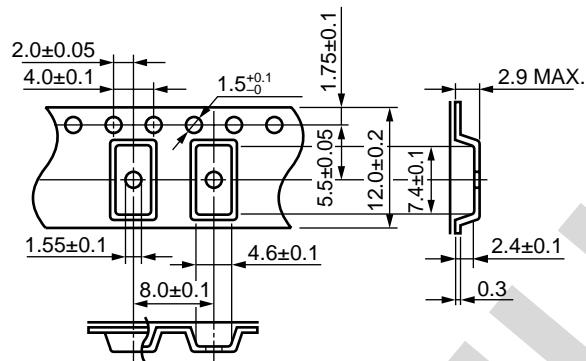
**Remark** The graphs indicate nominal characteristics.

NORMALIZED TURN-ON TIME vs.  
AMBIENT TEMPERATURENORMALIZED TURN-OFF TIME vs.  
AMBIENT TEMPERATURE

**Remark** The graphs indicate nominal characteristics.

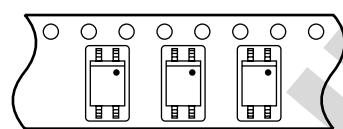
## TAPING SPECIFICATIONS (in millimeters)

## Outline and Dimensions (Tape)

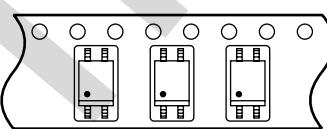


## Tape Direction

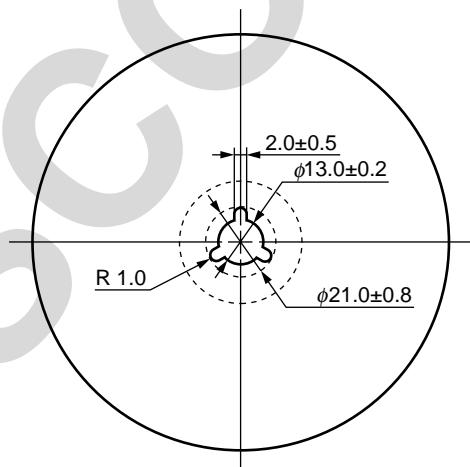
PS7200A-1A-E3



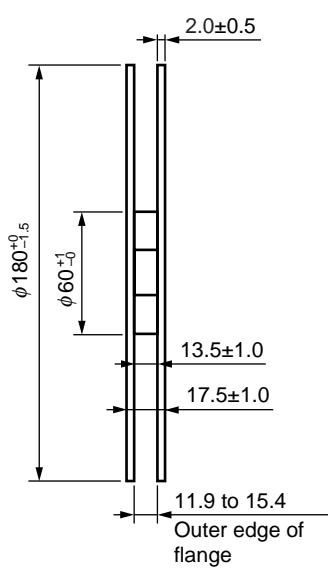
PS7200A-1A-E4



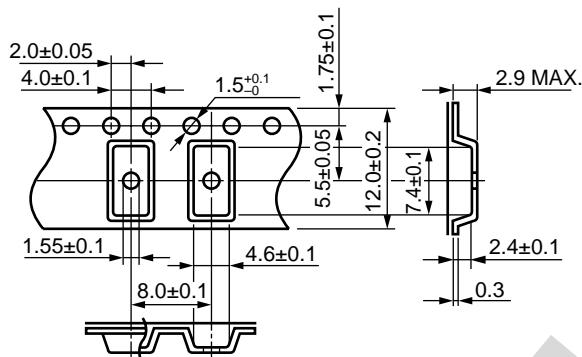
## Outline and Dimensions (Reel)



Packing: 900 pcs/reel



## Outline and Dimensions (Tape)



## Tape Direction

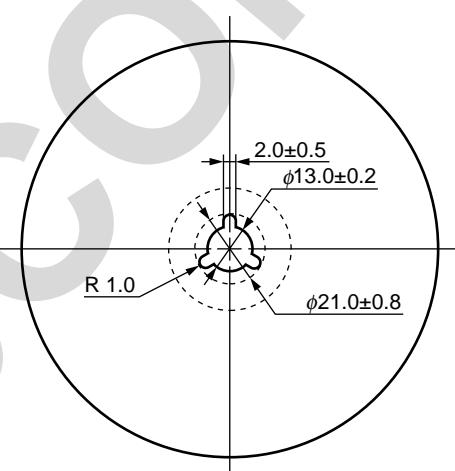
PS7200A-1A-F3



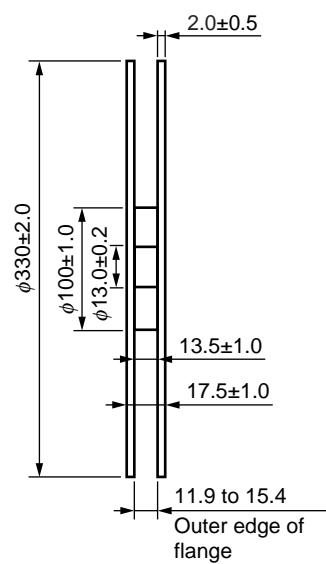
PS7200A-1A-F4



## Outline and Dimensions (Reel)



Packing: 3 500 pcs/reel

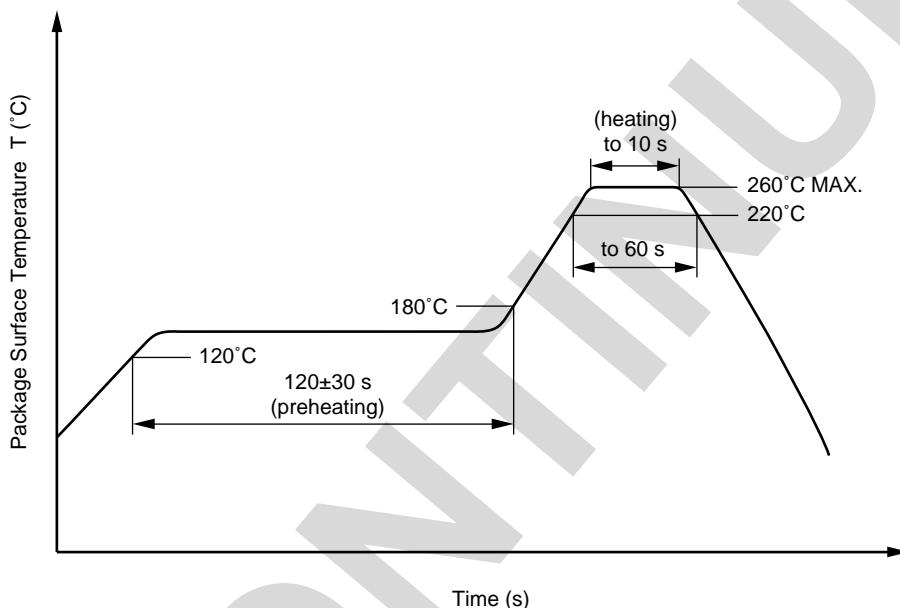


## RECOMMENDED SOLDERING CONDITIONS

### (1) Infrared reflow soldering

- Peak reflow temperature 260°C or below (package surface temperature)
- Time of peak reflow temperature 10 seconds or less
- Time of temperature higher than 220°C 60 seconds or less
- Time to preheat temperature from 120 to 180°C 120±30 s
- Number of reflows Three
- Flux Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

Recommended Temperature Profile of Infrared Reflow



### (2) Wave soldering

- Temperature 260°C or below (molten solder temperature)
- Time 10 seconds or less
- Preheating conditions 120°C or below (package surface temperature)
- Number of times One
- Flux Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

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### (3) Soldering by soldering iron

- Peak temperature (lead part temperature) 350°C or below
- Time (each pins) 3 seconds or less
- Flux Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

- (a) Soldering of leads should be made at the point 1.5 to 2.0 mm from the root of the lead.
- (b) Please be sure that the temperature of the package would not be heated over 100°C.

### (4) Cautions

- Fluxes Avoid removing the residual flux with freon-based and chlorine-based cleaning solvent.

**<R> USAGE CAUTIONS**

1. Protect against static electricity when handling.
2. Avoid storage at a high temperature and high humidity.

DISCONTINUED

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M8E 02.11-1

**Caution****GaAs Products**

This product uses gallium arsenide (GaAs). GaAs vapor and powder are hazardous to human health if inhaled or ingested, so please observe the following points.

- Follow related laws and ordinances when disposing of the product. If there are no applicable laws and/or ordinances, dispose of the product as recommended below.
- 1. Commission a disposal company able to (with a license to) collect, transport and dispose of materials that contain arsenic and other such industrial waste materials.
- 2. Exclude the product from general industrial waste and household garbage, and ensure that the product is controlled (as industrial waste subject to special control) up until final disposal.
- Do not burn, destroy, cut, crush, or chemically dissolve the product.
- Do not lick the product or in any way allow it to enter the mouth.

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**►For further information, please contact****NEC Compound Semiconductor Devices Hong Kong Limited**

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